

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	10	c-plane adj gan adj wafer	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:45
L2	144	c-plane adj gan	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 11:48
L3	1	257/194.ccls. and isolation and obtuse	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 12:00
L4	7	257/194.ccls. and isolation and acute	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 12:01
L5	34	c-plane adj gan and n-face	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 12:28
L6	33	c-plane adj gan adj substrate	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 12:30
L7	14	2 and p-n	US_PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 12:34

L8	2	"US 20070121690"	US-PGPUB; USPAT; USOCR; DERWENT	OR	ON	2009/07/02 14:10
L9	2	("6468882").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/07/02 15:01
L10	195	dry adj etching and gan and light and roughening	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2009/07/02 15:07

7/2/2009 3:26:38 PM